EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	758	257/E21.596,E21.238.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/03/27 14:09
L3	0	1 and puls$3 with laser and (dicing cutting singulating separating) with (chip substrate die wafer board) and program $5 and puls$3 with (energy rate overlap) and (chip substrate die wafer board) with strength	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/03/27 14:12
L4	4	1 and puls$3 with laser and (dicing cutting singulating separating) with (chip substrate die wafer board) and program $5 and puls$3 with (energy rate overlap) and (chip substrate die wafer board) with strength	US-PGPUB; USPAT; USOCR	OR	ON	2010/03/27 14:13
S1	19	((ADRIAN) near2 (BOYLE)).INV.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 10:12
S2	9	S1 and (dice or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 10:52
S3	9	S1 and (dice or dicing) and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 11:04
S4	13	((ADRIAN) near2 (BOYLE)).INV.	EPO; JPO; DERWENT	ADJ	ON	2008/11/04 11:12
S5	5	S4 and (dice or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 11:19
S6	2	((OONAGH) near2 (MEIGHAN)).INV.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 11:21
S7	1	S6 and (dice or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 11:22

S8	4	((OONAGH) near2 (MEIGHAN)).INV.	EPO; JPO; DERWENT	ADJ	ON	2008/11/04 11:22
S9	2	S8 and (dice or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 11:22
S10	0	wo0072224a	DERWENT	ADJ	ON	2008/11/04 11:27
S11	1	"0072224"	DERWENT	ADJ	ON	2008/11/04 11:27
S12	1	"0234455"	DERWENT	ADJ	ON	2008/11/04 11:33
S13	312836	laser	DERWENT	ADJ	ON	2008/11/04 12:45
S14	12278	dice or dicing	DERWENT	ADJ	ON	2008/11/04 12:45
S15	879634	substrate	DERWENT	ADJ	ON	2008/11/04 12:45
S16	39	controlled near (dice or dicing)	DERWENT	ADJ	ON	2008/11/04 12:46
S17	169	controlled same (dice or dicing)	DERWENT	ADJ	ON	2008/11/04 12:46
S18	265	S13 and S14 and S15	DERWENT	ADJ	ON	2008/11/04 12:46
S19	3439	pulsed laser	DERWENT	ADJ	ON	2008/11/04 13:43
S20	5	S19 same S14	DERWENT	ADJ	ON	2008/11/04 13:43
S21	312836	S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:51
S22	1120595	laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:51
S23	67769	dice or dicing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:51
S24	2717362	substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:51

S25	0	control$3 samej(dice or dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:52
S26	5988	control$3 same (dice or dicing)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:52
S27	1332	S22 and S23 and S24 and S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:54
S28	347	S27 and pulse	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:54
S29	130	S28 and strength	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:55
S30	3	S29 and galvanometer and telecentric	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 13:55
S31	151	S22 same S23 same S24 same S26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 14:03
S32	2081	weibull	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 14:03
S33	4	weibull same die same strength same test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 14:04
S34	0	("2006/0249480").URPN.	USPAT	ADJ	ON	2008/11/04 14:07
S35	0	S31 and S32	USPAT	ADJ	ON	2008/11/04 14:08
S36	114	S31 and (cut or cutting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 14:25

S37	84190	substrate same (die or dice or dicing or diced)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:28
S38	3859139	pulse or switch or pulsed or switched	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:38
S39	1584	S37 same S38	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:39
S40	1120595	laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:39
S41	251	S39 same S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:40
S42	209	S41 and layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:43
S43	5	S42 and die strength	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:46
S44	1	("2005/0274702").URPN.	USPAT	ADJ	ON	2008/11/04 15:53
S45	14	S42 and (die same strength)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 15:55
S46	120	S42 and control	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 16:09

S47	46	("20010049205" | "20030015764" | "20030092241" | "20030129828" | "20030157781" | "20040004247" | "20040043149" | "20040044127" | "20040079728" | "20040102031" | "20040203254" | "20040206267" | "20050054213" | "20050112282" | "20050239264" | "20060038293" | "5314724" | "5525550" | "5527561" | "5597395" | "5705028" | "5985770" | "6030881" | "6102993" | "6133160" | "6184143" | "6300219" | "6316063" | "6335261" | "6352943" | "6352953" | "6372669" | "6503330" | "6511539" | "6531377" | "6534395" | "6534802" | "6540838" | "6551339" | "6551399" | "6586349" | "6780789" | "6802944" | "6861334" | "6867152" | "6908862"). PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 16:39
S48	0	S47 and (dice or dicing or die) and (laser same (pulse or switch or pulsed or switched or chop or chopped or pulsing or switching or chopping))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 16:41
S49	7	S47 and laser	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 16:42
S50	163	((dicing or dice or die or diced) same (cutting or cut) same (laser near (pulse or pulsed or step or stepped or switch or switching or pulsing or stepping)))	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 17:27
S51	49	S50 and (crack or shock)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 17:32
S52	41	S50 and (crack or shock) and substrate	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/04 17:33
S53	142	weibull and die and strength and test	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 17:51

S54	142	S53 and (die or dice or diced)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 17:52
S55	43	S54 and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 17:53
S56	21	S38 and S55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 17:53
S57	49	program same controlled same pulsed same laser same beam	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 17:59
S58	9	S57 and (dice or diced or die)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/04 17:59
S59	6905	substrate same diced	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:16
S60	83011	substrate same (diced or die or dice or dicing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:18
S61	238735	laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:32
S62	8337	S60 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:33

S63	1267	(laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)) same (substrate same (diced or die or dice or dicing))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:35
S64	542	(laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)) same (substrate same (diced or die or dice or dicing)) same layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:36
S65	211	(laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)) same (substrate same (diced or die or dice or dicing)) same layer and gas	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:37
S66	23	(laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)) same (substrate same (diced or die or dice or dicing)) same layer and gas and (taper or tapered or tapering)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 08:46
S67	1	("2005/0236378").URPN.	USPAT	ADJ	ON	2008/11/05 08:59
S68	18	("20020005958" | "20020039186" | "20020167326" | "20040150820" | "20040226926" | "20050236378" | "5486701" | "5517315" | "5555474" | "5564830" | "5581346" | "5588005" | "5588995" | "6128087" | "6275295" | "6278809" | "6376797" | "6563130"). PN. OR ("7238912").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/05 09:00

S69	145	(laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)) same (substrate same (diced or die or dice or dicing)) same layer and gas and cut	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 09:22
S70	12	(laser same (pulse or pulsed or step or stepped or switch or switching or switched or pulsing or stepping or modelock or modelocked or modelocking)) same (substrate same (diced or die or dice or dicing)) same layer and gas and cut and file	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/05 09:26
S71	13	("3824678" | "4169976" | "5916460" | "6159832" | "6261919" | "6333485" | "6365443" | "6376797" | "6440773").PN. OR ("6770544").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 16:40
S72	19	("20010009250" | "20020033558" | "4547651" | "5057664" | "5751585" | "5779753" | "5841099" | "5843363" | "6130009" | "6255621"). PN. OR ("6676878").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 16:57
S73	1243	semiconduct$3 and ((pulse or pulsed or pulsing) with laser) and ((dicing or cutting) with substrate) and layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/24 17:36
S74	202	S73 and die and gas	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/24 17:40
S75	58	S74 and crack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/24 17:42
S76	1550	438/460,463.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 17:54
S77	751	S76 and laser	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 17:56

S78	212	S76 and ((pulse or pulsed or pulsing) with laser)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 17:56
S79	1350	438/113.ccls.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 18:41
S80	500	S79 and laser	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 18:41
S81	54	S80 and ((pulse or pulsed or pulsing) with laser)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 18:41
S82	29	S81 not S78	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 18:42
S83	1	(pulse or pulsed or pulsing) with laser and (dicing or cutting or dice or die or cut) with (program (control or controlled)) and substrate with layer	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 18:58
S84	2429	(pulse or pulsed or pulsing) same laser and (dicing or cutting or dice or die or cut) same (control or controlled) and substrate same layer	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/24 19:00
S85	2081	(pulse or pulsed or pulsing) with laser and (dicing or cutting or dice or die or cut) same (control or controlled) and substrate same layer	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/25 08:46
S86	1900	(pulse or pulsed or pulsing) with laser and (dicing or cutting or dice or die or cut) same (control or controlled) and substrate with layer	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/25 08:47
S87	16	S86 and die with strength	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/11/25 08:49
S88	289	program and controlled and dicing and substrate and pulsed and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 08:58
S89	47	S88 and crack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:05
S90	9126	"47" and laser with pulsed	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:06

S91	5	"I47" and (laser with pulsed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:07
S92	5	"I47" and (laser with pulsed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:07
S93	165	S88 and (laser with pulsed)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:08
S94	17076	substrate with layer and (semiconduct or semiconductor or semiconducting or semiconductive) and (laser with (pulse or pulsed or pulsing))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:47
S95	7264	S94 and (dicing or die or dice or cut or cutting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 09:50
S96	963	S95 and crack	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:03
S97	3923	S95 and (crack or break or damage or shock)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:04
S98	3923	S97 and layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:04
S99	3200	S98 and damage	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:11
S100	2560	S99 and control	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:12

S101	989	S100 and scan	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:13
S102	8	S101 and (die with strength)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:15
S103	552	PROGRAM and (CONTROL or controlled or controlling) and (DICE or dicing or die) and SUBSTRATE and (PULSE or pulsed or pulsing) and LASER and MECHANISM and (DRIVE or driver or driving) and (CUT or cutting or dice or dicing or diced) and STRATEGY and FILE and (SCAN or scanned or scanning) and LAYER and RESPECTIVE and SELECT	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:22
S104	550	S103 and strength	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:28
S105	154	S104 and gas	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:32
S106	111	S105 and lens	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:33
S107	10	program with ((control or controlled or controlling) and (dice or dicing or diced)) and ((dice or diced or dicing) with (substrate or wafer)) and ((pulse or pulsed or pulsing) with laser)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 10:50
S108	8506	(dice or dicing or diced) near3 substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 11:33

S109	6483	S108 and semiconduct$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 11:34
S110	479	S109 and (pulse or pulsed or pulsing or step or stepped or stepping) near3 (laser)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 11:35
S111	2	"5,185,295".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 11:58
S112	2	"6,023,039".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 12:25
S113	2	("2002/0088780").URPN.	USPAT	ADJ	ON	2008/11/25 12:32
S114	0	("2004/0075717").URPN.	USPAT	ADJ	ON	2008/11/25 13:01
S115	0	"10273381"	USPAT	ADJ	ON	2008/11/25 13:02
S116	2	"6586707".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/25 18:02
S117	3	weibull with die with strength with test	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:23
S118	5	weibull with die with strength	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:24
S119	11	weibull with die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:25
S120	2036	weibull	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:30

S121	487	S120 and semiconduct$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:30
S122	189	S121 and strength	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:30
S123	42	S122 and die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:31
S124	351	telecentric with scan with lens	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:45
S125	93	S124 and (map or mapping) and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:47
S126	36	S124 and (map or mapping) and (laser with (pulse or pulsed or pulsing))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 11:47
S127	7	laser with (dice or diced or dicing or cutting or cut) and laser with substrate and laser with (pulsed or pulse or pulsing) and control and strategy and galvanometer and (scan or scanned or scanning) and telecentric and layer and gas and crack	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/26 13:14
S128	35	(US-20020127824-$ or US-20040137700-$ or US-20040027980-$ or US-20030127428-$ or US-20020115235-$ or US-20040259329-$ or US-20020088780-$ or US-20030155328-$ or US-20040075717-$ or US-20040252730-$ or US-20020019074-$).did. or (US-6770544-$ or US-6806544-$ or US-6960739-$ or US-6676878-$ or US-5543365-$ or US-4525179-$ or US-6671294-$ or US-	US-PGPUB; USPAT; DERWENT	ADJ	ON	2008/12/01 16:22

		5916460-$ or US-5841099-$ or US-6159825-$ or US-6413839-$ or US-6902990-$ or US-6586702-$ or US-6522386-$ or US-6941536-$ or US-3629545-$ or US-5057184-$ or US-5151389-$ or US-5214261-$ or US-5185295-$ or US-6023039-$ or US-6586707-$ or US-6951120-$).did. or (JP-2005142365-$).did.				
S129	0	S128 and die near5 strength	US-PGPUB; USPAT; DERWENT	ADJ	ON	2008/12/01 16:23
S130	14	S128 and strength	US-PGPUB; USPAT; DERWENT	ADJ	ON	2008/12/01 16:23
S131	20	S128 and die	US-PGPUB; USPAT; DERWENT	ADJ	ON	2008/12/01 16:24
S132	10	S130 and die	US-PGPUB; USPAT; DERWENT	ADJ	ON	2008/12/01 16:24
S133	45	("20020031899" | "20020033558" | "20020063361" | "20020125232" | "20030209528" | "3626141" | "3814895" | "3816700" | "4237601" | "4336439" | "4543464" | "4562333" | "4664739" | "4769523" | "4906011" | "4921564" | "5057664" | "5138131" | "5324012" | "5387776" | "5611946" | "5626777" | "5627109" | "5656186" | "5703713" | "5801356" | "5809987" | "5811751" | "5961852" | "5963364" | "5987920" | "5994205" | "6057525" | "6107162" | "6121118" | "6126520" | "6130401" | "6182733" | "6365429" | "6413839" | "6509546" | "6586707" | "6664498" | "6676878" | "RE33947"). PN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/02 18:07
S134	23	S133 and mirror	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/02 18:07

S135	52	("3629545" | "3699644" | "3824678" | "3970819" | "4046985" | "4224101" | "4543464" | "4729971" | "4851371" | "4865686" | "4964212" | "4992393" | "5075201" | "5151389" | "5185295" | "5214261" | "5385633" | "5543365" | "5552345" | "5631190" | "5641416" | "5864171" | "5872046" | "5912477" | "5922224" | "5932118" | "5976691" | "6117347" | "6140151" | "6225194"). PN. OR ("6413839").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/02 18:24
S136	221402	"52" and tape	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/02 18:25
S137	25	S135 and tape	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/02 18:25
S138	1	"5435876".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 08:51
S139	1	S138 and tape	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 08:51
S140	101	("4338149" | "4793883" | "4897141" | "4925515" | "4961804" | "5006202" | "5098501" | "5110388" | "5187007").PN. OR ("5435876").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 08:53
S141	32	S140 and tape	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 08:53
S142	432	(semiconductor or semiconductive or semiconducting) and (tape near5 (UV or ultraviolet or (ultra near violet))) and (dice or dicing or diced) and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:11
S143	401	(semiconductor or semiconductive or semiconducting) and (tape near3 (UV or ultraviolet or (ultra near violet))) and (dice or dicing or diced) and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:11
S144	12	S143 and tape with polyolefin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:12

S145	14	S142 and tape with polyolefin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:19
S146	2	S145 not S144	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:19
S147	2557	tape near3 (UV or ultraviolet or (ultra violet))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:42
S148	643	S147 and laser and (dice or dicing or diced or cut or cutting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:44
S149	23	S148 and tape with polyolefin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:44
S150	9	S149 and transparent	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:51
S151	7	S149 and transparent near5 tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 09:59
S152	19	((ADRIAN) near2 (BOYLE)).INV.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 10:04
S153	1	S152 and tape with polyolefin	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 10:04
S154	6	S152 and tape	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 10:05
S155	11	("4270317" | "4473424" | "Re32571").PN. OR ("5358590").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 10:09
S156	6	S155 and tape	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/12/03 10:10
S157	106	die and wall and oxidation and gas and inert and passive and machining	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 10:34

S158	11	S157 and (stop or stopping or impede or impeding or prevent or preventing) near3 oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 10:36
S159	69923	(machining or dicing or cutting or cut or dice) with gas	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:14
S160	2952	S159 and gas with oxidation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:15
S161	347	S159 and gas with ((prevent or preventing or stop or stopping or impede or resist or control or elimitate or limit) near3 oxidation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:23
S162	228	S161 and gas with inert	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:24
S163	4	S161 and gas with (inert and passive)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:25
S164	4	S162 and gas with passive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:33
S165	9	S162 and passive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:33
S166	224	S162 and (dicing or cutting or diced or cut)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:34
S167	55	S162 and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/12/03 11:34
S168	4	("2002/0019074").URPN.	USPAT	ADJ	ON	2008/12/03 17:58

S169	0	S168 and weibull	USPAT	ADJ	ON	2008/12/03 17:59
S170	20	((ADRIAN) near2 (BOYLE)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/06 21:19
S171	2	((OONAGH) near2 (MEIGHAN)).INV.	US-PGPUB; USPAT; USOCR	OR	ON	2009/11/06 21:22
S172	90	puls$3 near3 laser and (dic$3 cut$3 singulat$3) and control and (storage memory) and pulse with (energy and rate and overlap) and damage and (die wafer chip board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/11/06 21:27

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	0	(puls$3 near3 laser and (dicing cutting singulating separating) with (die chip wafer board substrate) and (memory storage) and lens and energy near3 density and (die chip wafer board substrate) with strength and damage and (programmable controllable) near3 laser).clm.	USPAT; UPAD	OR	ON	2010/03/27 14:23
L6	0	(puls$3 near3 laser and (dicing cutting singulating separating) with (die chip wafer board substrate) and (memory storage) and lens and energy near3 density and (die chip wafer board substrate) with strength and damage and (programmable controllable) near3 laser).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2010/03/27 14:24
L7	1	(puls$3 near3 laser and (dicing cutting singulating separating) with (die chip wafer board substrate) and (memory storage) and lens and energy near3 density and (die chip wafer board substrate) with strength and damage and program near2 controlled near3 laser).clm.	US-PGPUB; USPAT; UPAD	OR	ON	2010/03/27 14:25

3/27/2010 2:26:32 PM
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